

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

: KUO, Frank

Title

: ENCAPSULATION METHOD AND LEADFRAME FOR LEADLESS
SEMICONDUCTOR PACKAGES (As Amended)

Docket No.

: VISH-4123.DIV

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend the specification of the prior application, US Application 10/113,526 as
originally filed on March 28, 2002, as follows: